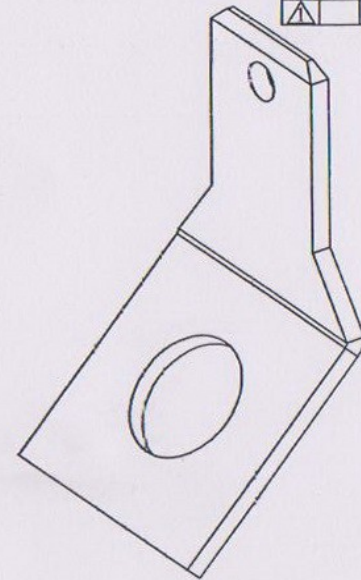
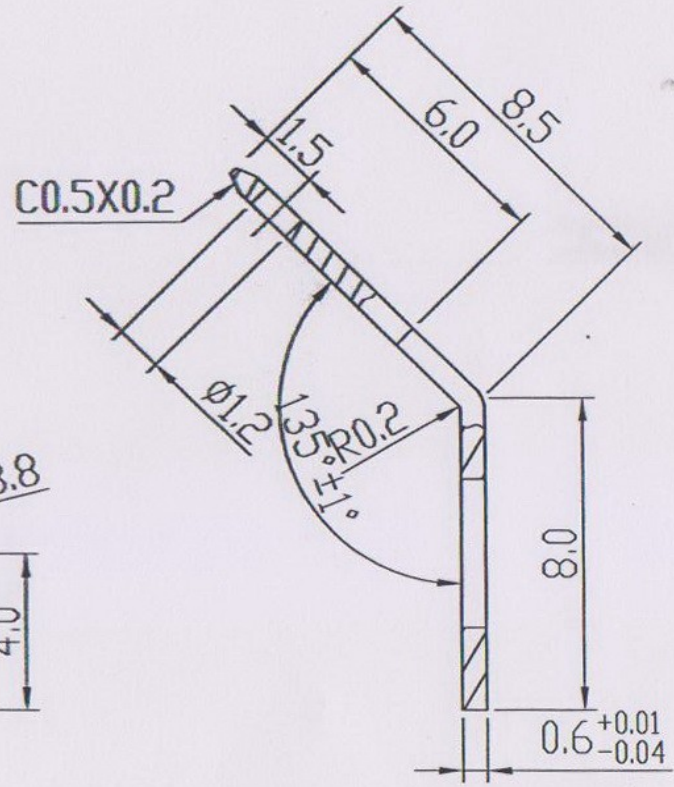
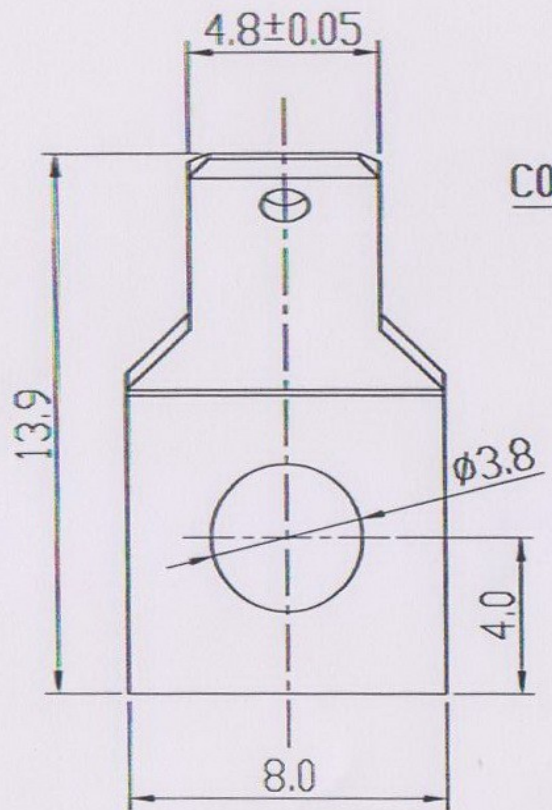


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	DATE
△		增加材质牌号, 修改电镀标准	YHG	10/15/09



- Notes:
1. Material: H62 H/2, T=0.6mm;
 2. Plating: Cu plated at the bottom is more than 2um; Ni plated on the surface is more than 2um; Sn plated at the bottom is more than 4um;
 3. Undimensioned Tolerances:

Pitch range in mm		Nominal dimension range in mm										
to	over	to	over	to	over	to	over					
6	6	10	10	30	30	60	60	100	100	150	150	∩
±0.10	±0.15	±0.25	±0.2	±0.3	±0.5	±0.7	±1.0	±0.05/0				□



1	K5	C0510	H62	SnCe	
ITEM	NAME OF PART	NO. OF PART	Q*TY	MATERIAL	NOTES
	MM (INCH)	DFTD YHG	DATE 11/1/09	DEGSON 宁波高正电子有限公司 DEGSON ELECTRONICS CO., LTD	
	TOLERANCES EXCEPT AS NOTED	CHKD WJ	DATE 10/20/09	NAME K5-00A (H)	
	MM	MFD	DATE	DRAWING NO. K5-E01	
	.0 ±	APPV Hang	DATE 10/13/09	/PART NO.	
	.00 ±	MATERIAL :		SIZE A4	
	.000 ±	ANGLES ± 1°	G.E. :	REV T1	
		FINISH:		10/15/09	
		THIRD ANGLE PROJECTION	SCALE 1:1	DO NOT SCALE DRAWING	
				SHEET 1 OF 1	